

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **10041601 A**

(43) Date of publication of application: **13.02.98**

(51) Int. Cl.

H05K 1/11
H05K 3/42

(21) Application number: **08193796**

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(22) Date of filing: **24.07.96**

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(54) **PRINTED WIRING BOARD AND ITS
MANUFACTURE**

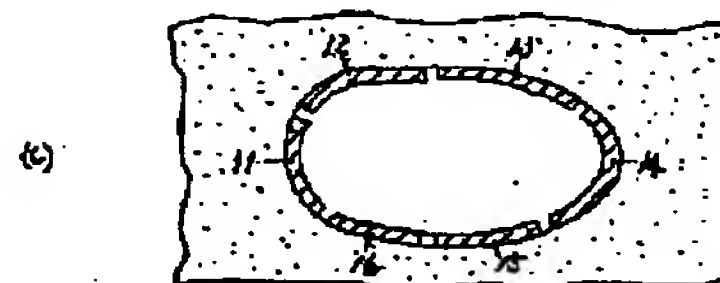
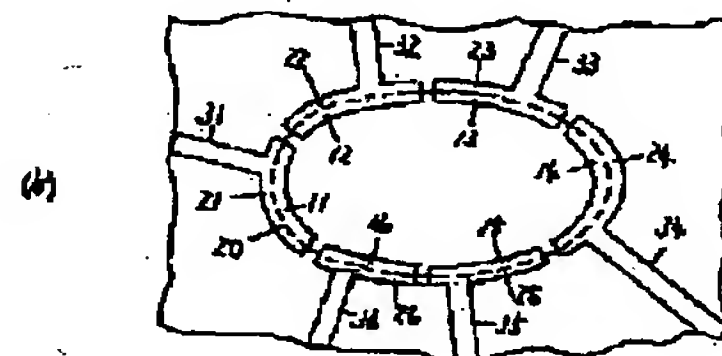
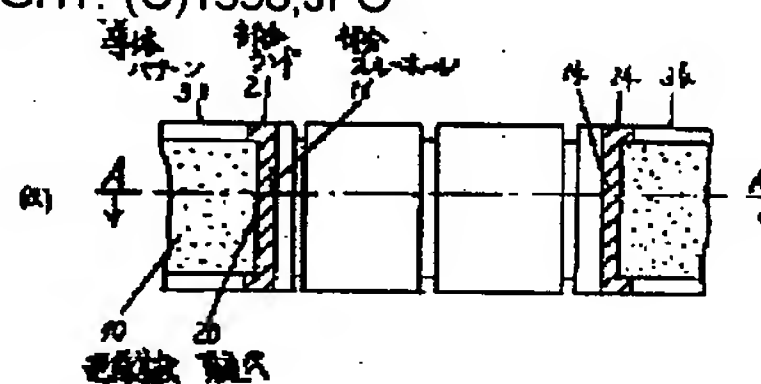
(57) Abstract:

PROBLEM TO BE SOLVED: To realize high density wiring when conducting patterns which are print-wired on both surfaces of an insulating board are mutually connected via through holes.

SOLUTION: An oblong penetrating hole 20 is formed in an insulating board 10. Six partial through holes 11-16 which stretch in the penetrating direction are separately insulated and stuck on the inner surface of the insulating board 10, in the state that neighboring holes along the inner periphery keep narrow intervals. Partial lands 21-26 are separately insulated and stuck on the respective surfaces of the insulating board 10 in the state that the lands are continuously linked with the respective end portions of other lands, keeping narrow intervals between neighboring lands. Corresponding conducting patterns 31-36 are connected to the respective partial lands 21-26. In the penetrating hole 20, the conducting patterns 31-36 of the respective surfaces are mutually connected via the six partial through holes 11-16, and high density wiring is enabled when penetrating connection of the insulating

board 10 is performed.

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